

Bill of Materials

TI DESIGNS

TIPD165: Isolated, Shunt-Based Current Sensing Reference Design
 AMC1304 Board BOM

Quantity	Designator	Value	Description	Manufacturer	Manufacturer Part Number 1
1	SH-J1	1x2	Shunt, 1.27 mm	Harwin Inc	M50-2000005
2	J2, J3	2x1	Conn Term Block, 2POS, 3.5mm	Phoenix Contact	1751248
1	U1		AMC1304Mx in 16-pin DW (SOI	Texas Instruments	AMC1304M25
1	C6	4.7uF	CAP, CERM, 4.7uF, 10V, +/-10%	Kemet	C0805C475K8PACTU
1	C3	5600pF	CAP, CERM, 5600pF, 25V, +/-5%	TDK	C2012C0G1E562J
3	C1, C5, C7	0.1uF	CAP, CERM, 0.1uF, 25V, +/-5%,	TDK	C3216C0G1E104J
1	T1		1:2.2 Isolation Transformer	Coilcraft	DA2304-AL
1	C2	2.2uF	CAP, CERM, 2.2uF, 16V, +/-10%	Taiyo Yuden	EMK212B7225KG-T
3	C4, C8, C9	10uF	CAP, CERM, 10uF, 16V, +/-10%	Taiyo Yuden	EMK212BJ106KG-T
3	FID1, FID2, FID3		Fiducial mark. There is nothing	N/A	
1	J1		1.27mm Pitch Multi-function Twc	Hirose	FX2-20S-1.27DS
2	D1, D2	0.385V	Diode, Schottky, 20V, 0.5A, SOI	ON Semiconductor	MBR0520LT1G
1	JP1		Header, 3-Pin	Sullins Connector Solutions	GRPB031VWVN-RC
1	!PCB1		Printed Circuit Board	Any	
2	R1, R3	20	RES, 20.0 ohm, 0.1%, 0.1W, 06	Yageo America	RT0603BRD0720RL
1	R2	50.5	RES, 50.5 ohm, 0.1%, 0.1W, 06	Yageo America	RT0603BRD0750R5L
1	U2		SN6501 transformer driver	Texas Instruments	SN6501

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